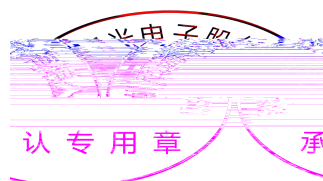
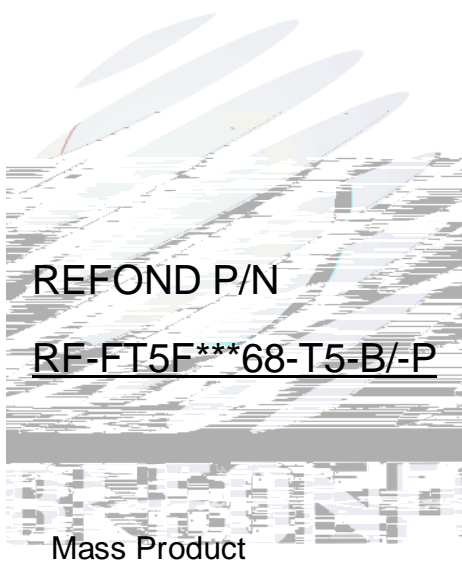
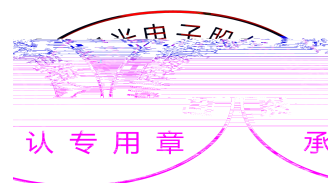


SPECIFICATION



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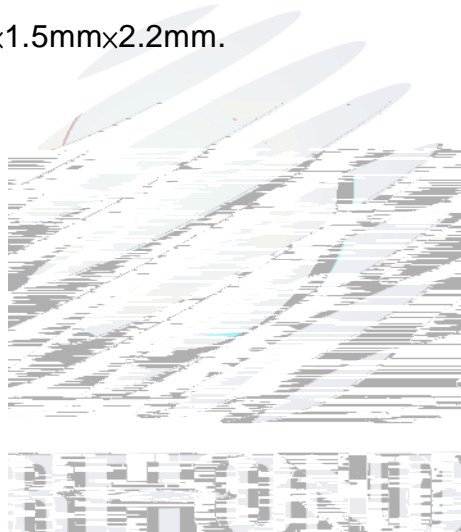


1. Description

1.1

The White LED, which was fabricated by using a blue chip and the phosphor.

Product Package:53.0mm×1.5mm×2.2mm.



53.0mm×1.5mm

1.4 Package Dimension

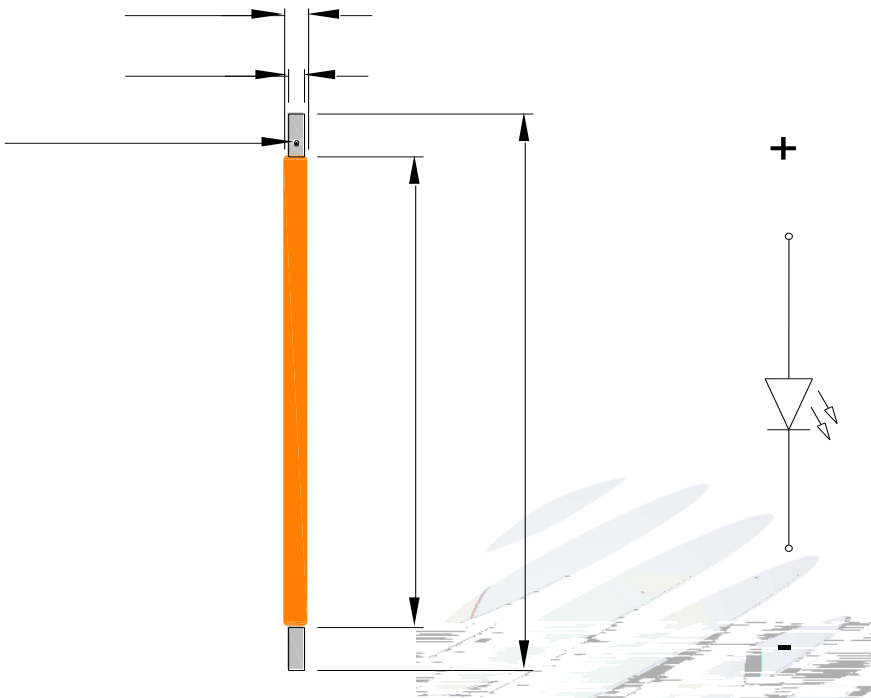


Fig.1-1 Top View

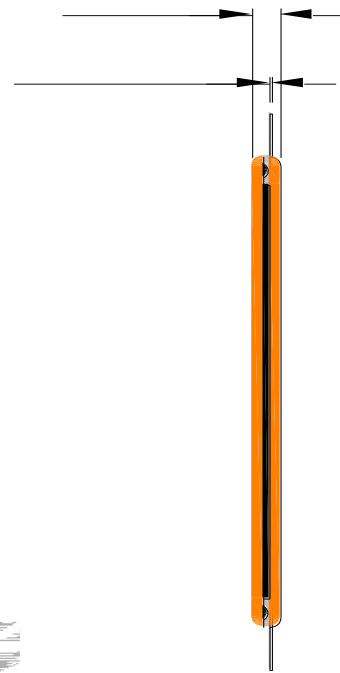


Fig.1-2 Side View

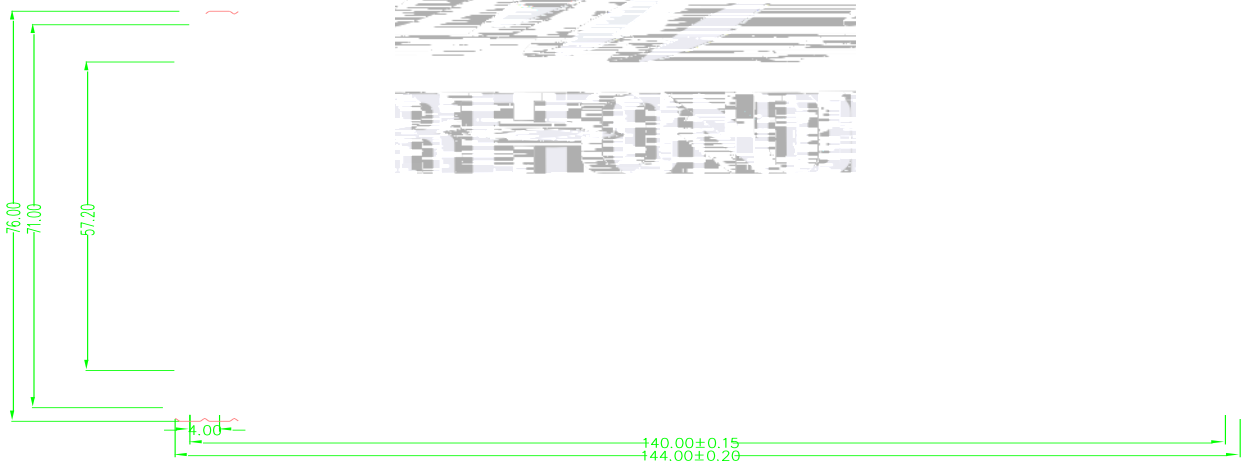


Fig.1-3 Whole Line View

Notes

All dimensions units are millimeters.

All dimensions tolerances are $\pm 0. \text{ mm}$ unless otherwise noted.



1.5 Product Parameters

Table 1-1 Electrical / Optical Characteristic Parameters

| Item | Symbol | Test Condition | Value | |
|--------------------|-----------------|----------------|-------|------|
| | | | Typ. | Max. |
| Forward Voltage | V_F | $I_F=20mA$ | --- | 72 |
| Leakage Current | V_F | $I_F=5\mu A$ | 50 | --- |
| Luminous Flux | Φ | $I_F=20mA$ | 230 | 280 |
| Viewing Angle | $2\theta_{1/2}$ | $I_F=20mA$ | --- | 360 |
| Solder Temperature | T_s | $I_F=20mA$ | --- | 105 |

 Table 1-2 Absolute Maximum Ratings at $T_s=25^\circ C$

| Parameter | Symbol | Units |
|--|--------|-------|
| Power Dissipation (P _{tot}) | | W |
| Storage Temperature (T _{stg}) | | °C |
| Operating Temperature (T _{op}) | | °C |
| Lead Temperature (T _l) | | °C |
| Welding Temperature (T _w) | | °C |
| Reflow Temperature (T _r) | | °C |

Notes



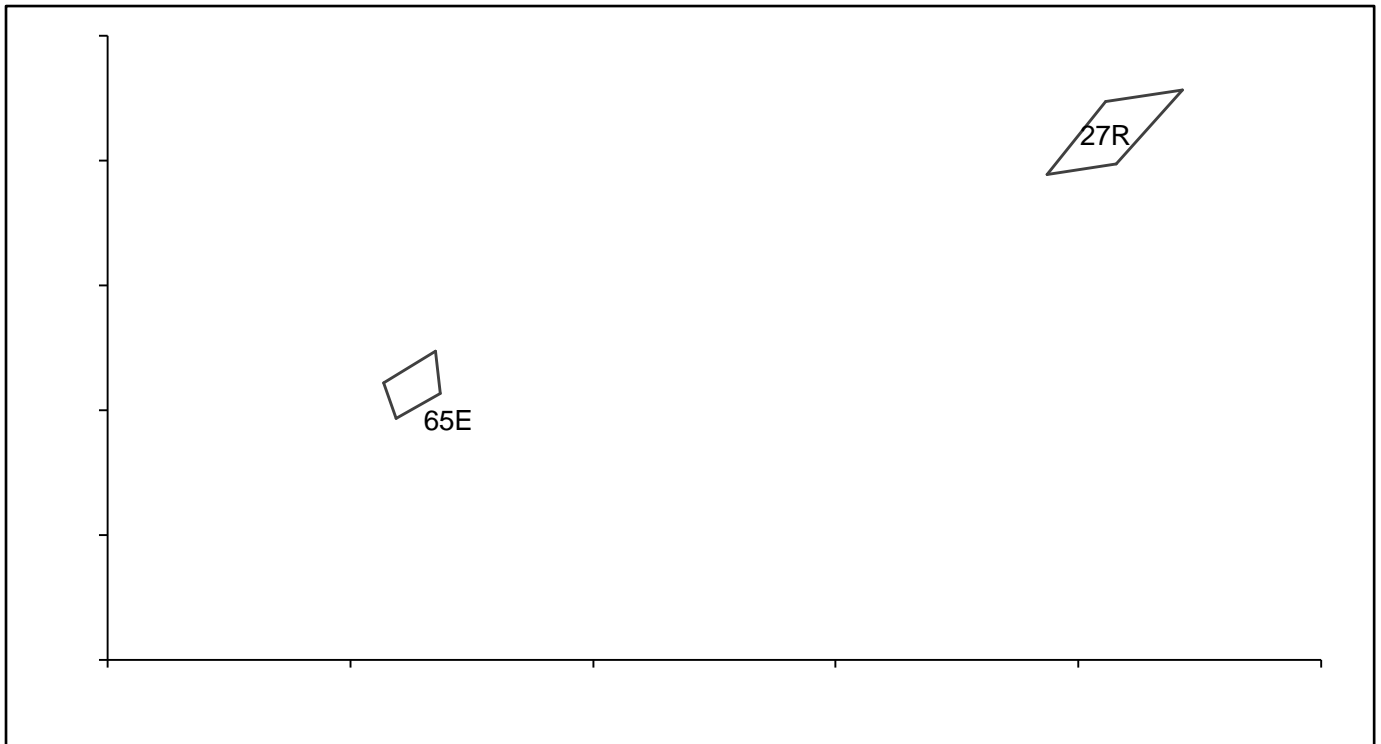


Fig. 1-6 The C.I.E Chromaticity Diagram CIE

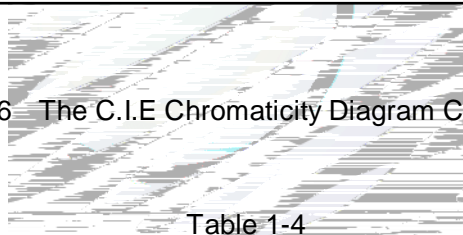
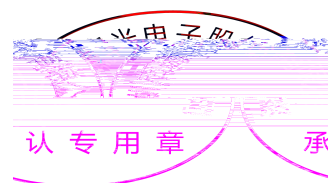


Table 1-4

| BIN CODE | CIE-X1 | CIE-Y1 | CIE-X2 | CIE-Y2 | CIE-X3 | CIE-Y3 | CIE-X4 | CIE-Y4 |
|----------|--------|--------|--------|--------|--------|--------|--------|--------|
| 27R | 0.4556 | 0.4289 | 0.4715 | 0.4327 | 0.4578 | 0.4088 | 0.4435 | 0.4055 |
| 65E | 0.3094 | 0.3272 | 0.3069 | 0.3387 | 0.3176 | 0.3487 | 0.3186 | 0.3354 |





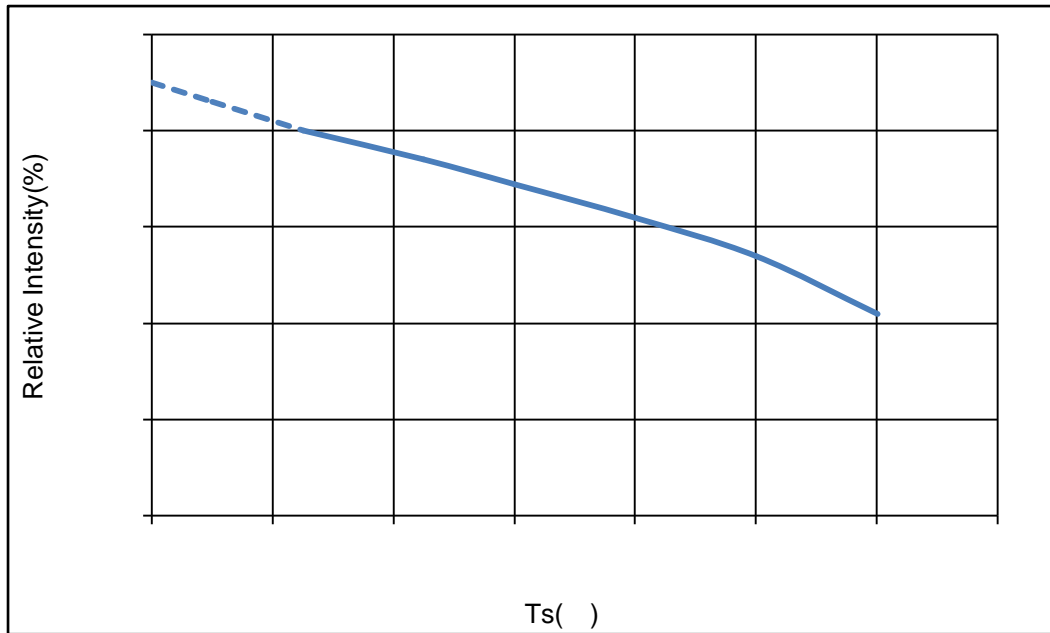


Fig. 1-9 Solder Temperature Vs Relative Intensity

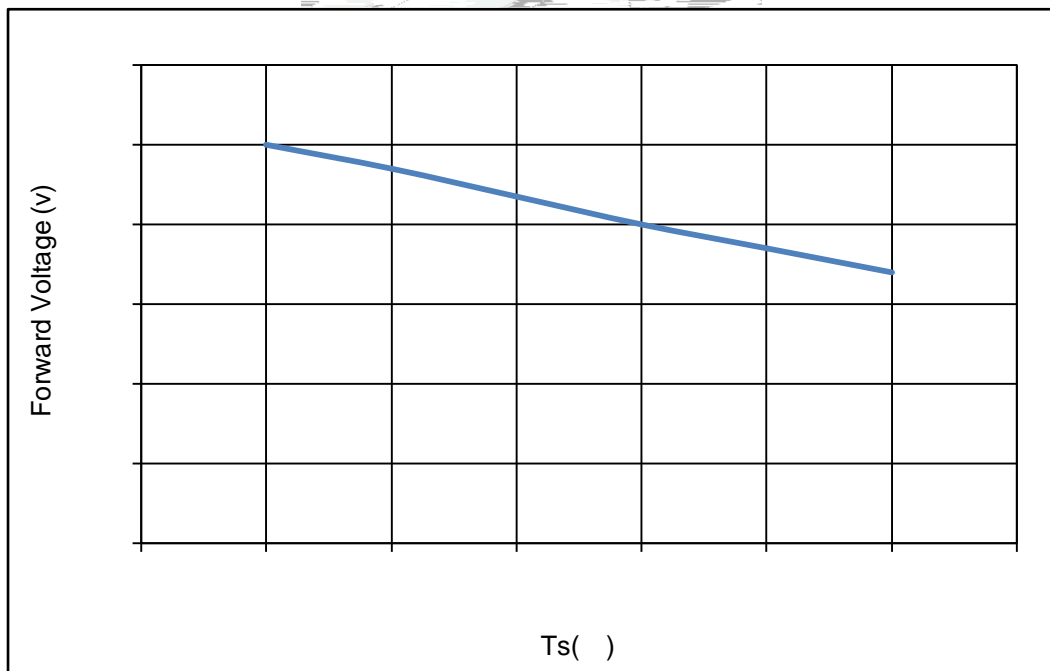
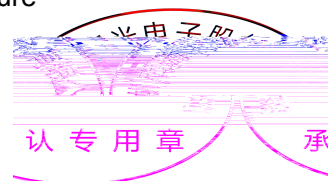


Fig. 1-10 Forward Voltage Vs Solder Temperature



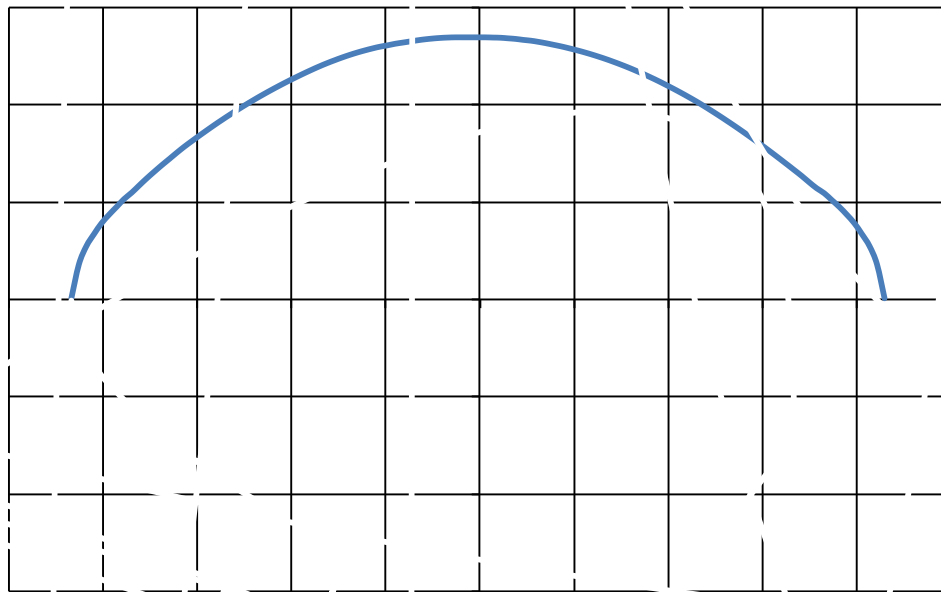


Fig. 1-11 Radiation diagram

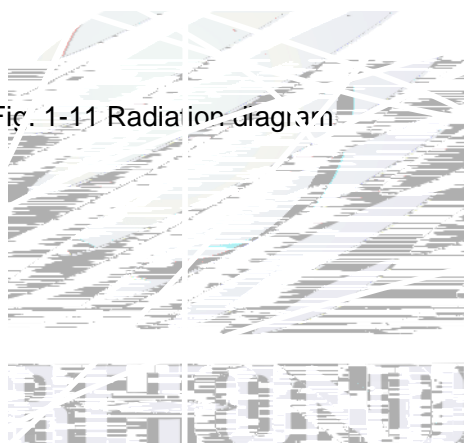
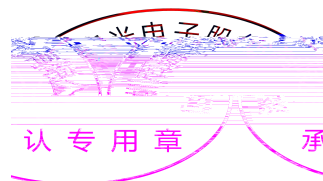


Fig. 1-12 Spectrum Distribution



2. Packaging

2.1 Packaging Specification

| | |
|------------------------|---------|
| Single :720pcs/box | 720pcs |
| Whole Row: 4320pcs/box | 4320pcs |

2.1.1 Suction box Dimension

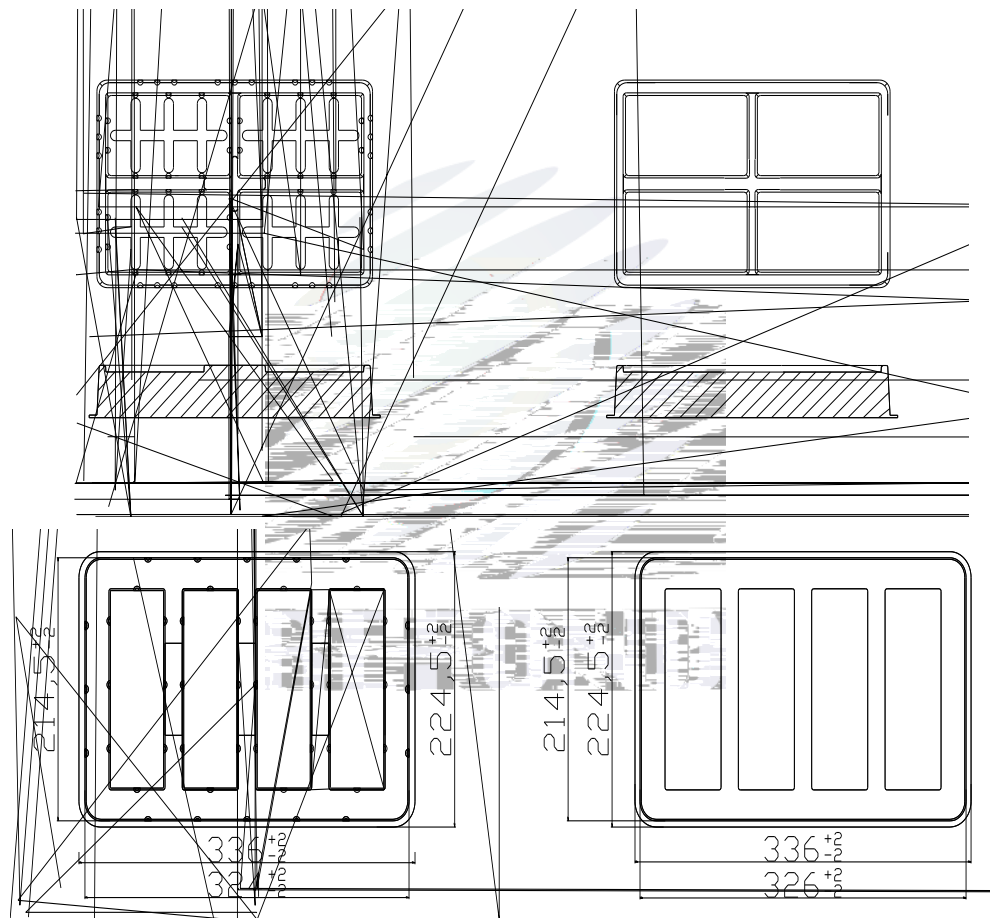


Fig.2-1 Suction box Dimension

Notes

The tolerances unless mentioned $\pm 0.1\text{mm}$. Unit : mm



2.1.2 Label Form Specification

| | |
|----------|-------------|
| PART NO. | Part Number |
| SPEC NO. | Spec Number |
| LOT NO. | Lot Number |
| BIN CODE | |

Fig. 2-2 Label

2.2 Moisture Resistant Packing

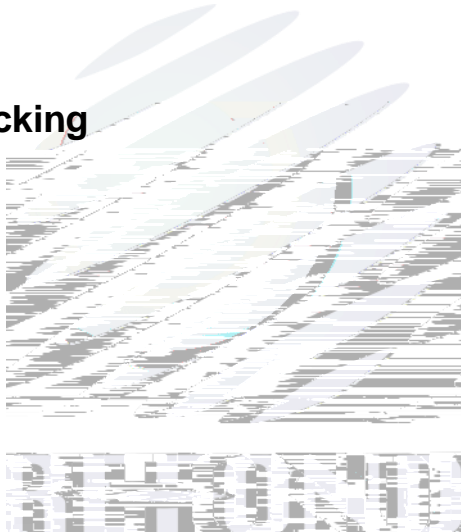


Fig.2-3 Moisture Resistant Packing

2.3 Cardboard Box

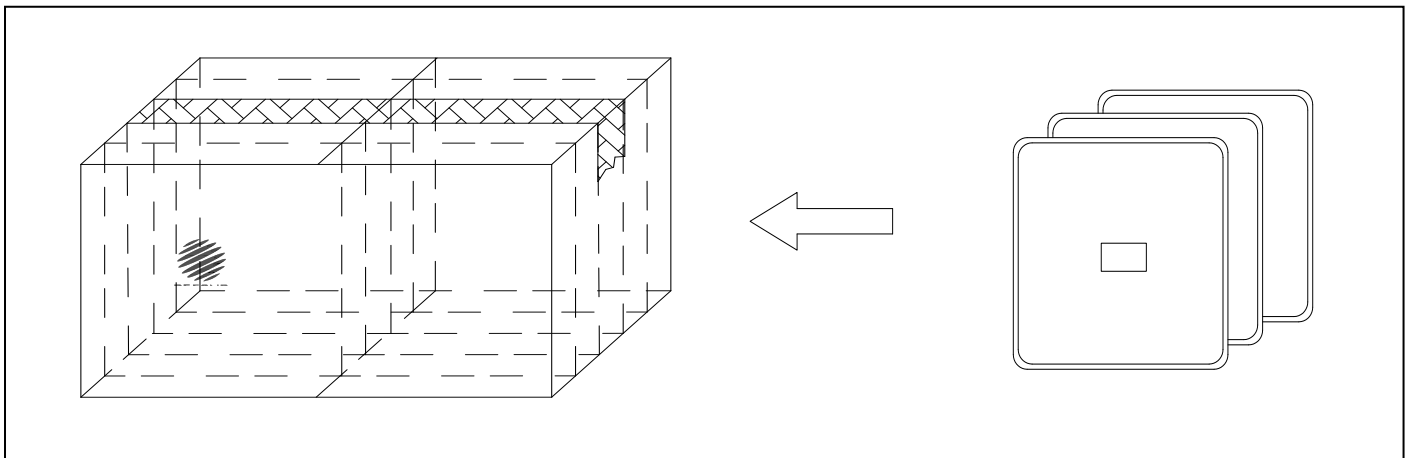


Fig.2-4 Cardboard Box

2.4 Reliability Test Items And Conditions

Table 2-2 Reliability Test Items And Conditions

| Test Items | Ref.Standard | Test Condition | Time | Quantity | Ac/Re / |
|---|------------------------|------------------------------------|-----------|----------|---------|
| Thermal Shock | JEITAED-4701 300307 | -40 15min ↑↓10s 100 15min | 100 cycle | 20pcs | 0/1 |
| Switching Test | / | 25 , On 2.5min ↑↓ Off 2.5min | 2500cycle | 20pcs | 0/1 |
| Life Test | JESD22-A108 | Ta=25 If=20mA | 1000hrs | 10pcs | 0/1 |
| High Temperature High Humidity Life Test | JESD22-A101 | 60 / 90%RH If=20mA | 500hrs | 10pcs | 0/1 |

認專用章 承

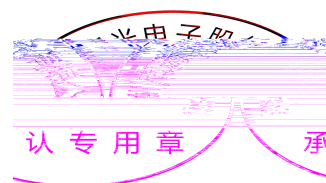
2.5 Criteria For Judging Damage

Table 2-3 Criteria For Judging Damage

| Test Items | Symbol | Test Condition | Criteria For Judgement | |
|-----------------|--------|----------------|------------------------|-----------------|
| | | | Min. | Max. |
| Forward Voltage | V_F | $I_F=20mA$ | - | Forward Voltage |
| Luminous Flux | Φ | $I_F=20mA$ | L.S.L*)x0.7 | Luminous Flux |

Notes

- 1.U.S.L: Upper standard level L.S.L: Lower standard level
2. The above reliability tests is based on the verification of a single/strip LED of Refond's existing experimental platform, the reliability experiment was taken under good heat dissipation conditions. when customers applies the LED to the series and parallel circuit, should take consideration of all the factors such as the current, voltage distribution, heat dissipation and others.
- 3.The technical information shown in the data sheets is limited to the typical characteristics and circuit examples of the referenced products. It does not constitute the warranting of industrial property nor the granting of any license.

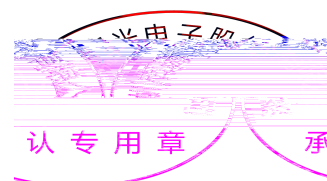


3. Handling Precautions

(1) LED operating environment and sulfur element composition cannot be over 100PPM in the LED mating usage material. This is provided for informational purposes only and is not a warranty or endorsement. LED

(2) In order to prevent external material from getting into the inside of LED, which may cause the malfunction of LED, the single content of Bromine element is required to be less than 900PPM, the single content of Chlorine element is required to be less than 900PPM, the total content of Bromine element and Chlorine element in the external materials of the application products is required to be less than 1500PPM. This is provided for informational purposes only and is not a warranty or endorsement.

(3) VOCs (Volatile organic compounds) emitted from materials used in the construction of fixtures can penetrate silicone encapsulants of LEDs and discolor when exposed to heat and photonic energy. The result can be a significant loss of light output from the fixture. Knowledge of the properties of the materials selected to be used in the construction of fixtures can help prevent these issues. Refond advises against the use of any chemicals or materials that have been found or are suspected to have an adverse effect on device performance or reliability. To verify compatibility, Refond recommends that all chemicals and materials be tested in the specific application and environment for which they are intended to be used. Attaching LEDs, do not use adhesives that outgas organic vapor.



(4) Handle the component along the side surface by using forceps or appropriate tools; Do not directly touch or Handle the silicone lens surface, it may damage the internal circuitry.

(5) In designing a circuit, the current through each LED can not exceed the absolute maximum rating specified for each LED. In the meanwhile, resistors for protection should be applied, otherwise slight voltage shift will cause big current change, burn-out may happen. The driving circuit must be designed to allow forward voltage only when it is ON or OFF. If the reverse voltage is applied to LED, migration can be generated resulting in LED damage.

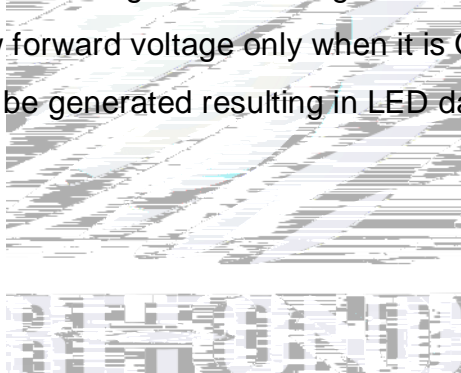


Table 4-1 Storage

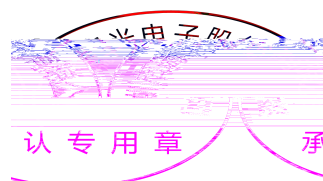
| Conditions | | Temperature | Humidity | Time |
|------------|-----------------------------|-------------|----------|-------------------------|
| Storage | Before Opening Aluminum Bag | 30 | 75% | Within 1 Year From Date |
| | After Opening Aluminum Bag | 30 | 60% | 24hours 24 |
| Baking | | 60 ± 5 | - | 24hours 24 |

(8) If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed after unpacking and based on the following condition (65±5) °C for above 24 hours.

If the package is flatulence or damaged, please notify the sales staff to assist.

(9) Similar to most Solid state devices; LEDs are sensitive to Electro-Static Discharge (ESD) and Electrical Over Stress (EOS).

(10) Other points for attention, please refer to our relevant information.





Declare

This specification is written both in English and in Chinese and the latter is formal.

